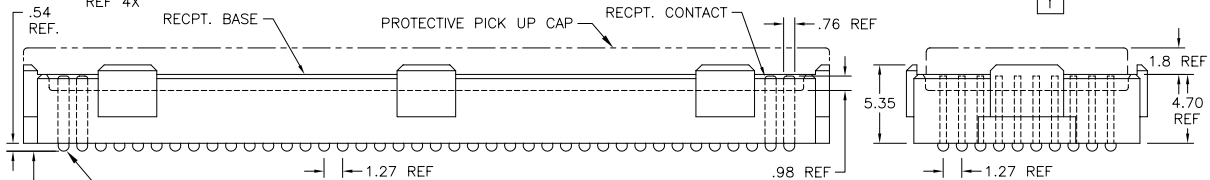
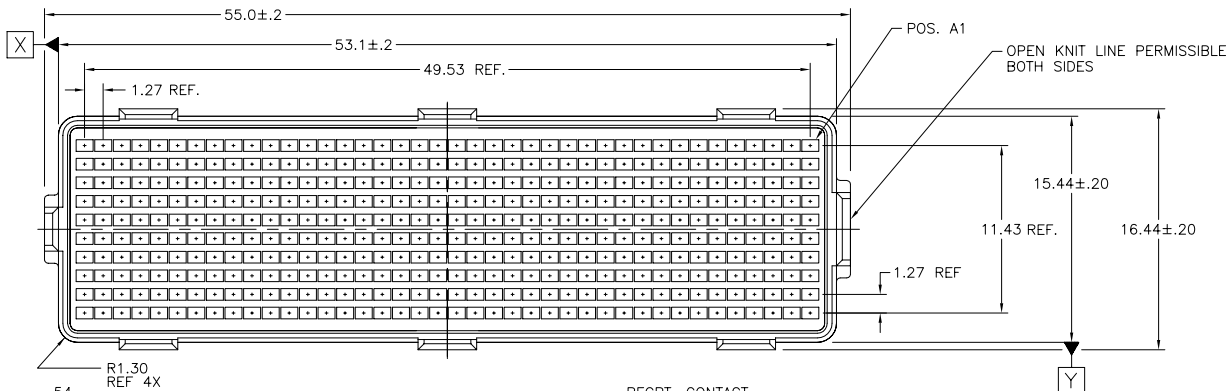


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PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
74388-001	YES	15u" (.38u") Au OVER Ni	SnPb
74388-001LF			SnAgCu LEAD FREE (5)(6)
74388-101	YES	30u" (.76u") Au OVER Ni	SnPb
74388-101LF			SnAgCu LEAD FREE (5)(6)
74388-201	YES	SEE NOTE 4.	SnPb
74388-201LF			SnAgCu LEAD FREE (5)(6)



Ø.760 SOLDER BALLS
NOTE 2.

⊕ Ø.30 X Y

▱ .203

mat'l code	SEE NOTE 1	surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family
tr	ec'n no	dr	date	tolerances unless otherwise specified		⊕	MEG-ARRAY
K	v06-0560	LP	2006/06/23	angles	Xx3	MM	title
-	-	-	-		XXXB		6mm RECEPT. ASSY
E	v90472	DRW	07/02/99	0° ±2'	XXXX051	scale 3:1	10 X 40= 400 POS.
F	v00181	HLJ	06/30/00	dr	D WAUGHEN	1.5.98	dwg no
G	v20006	DRW	01/07/02	engr	T LEMKE	1.5.98	sheet 1 of 3
H	v03-0679	DAI	06/19/03	chr	T LEMKE	1.5.98	size
J	v04-0940	VS	10/18/04	appd	T LEMKE	1.5.98	A4
sheet index	revision sheet	K	K	K			type
		1	2	3			CUSTOMER Drawing



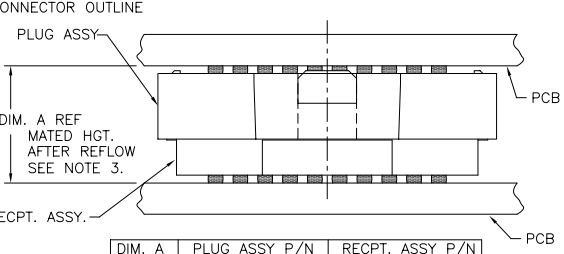
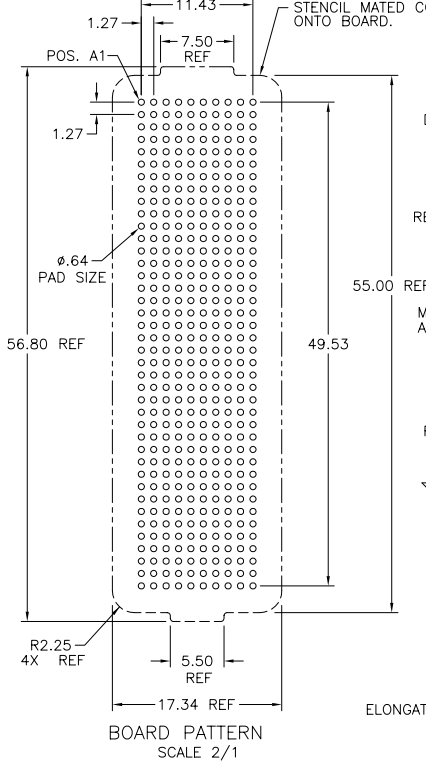
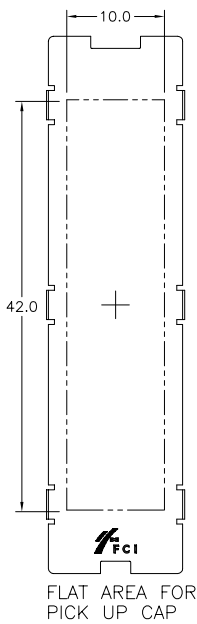
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PDM: Rev:K STATUS Released Printed: Oct 21, 2010



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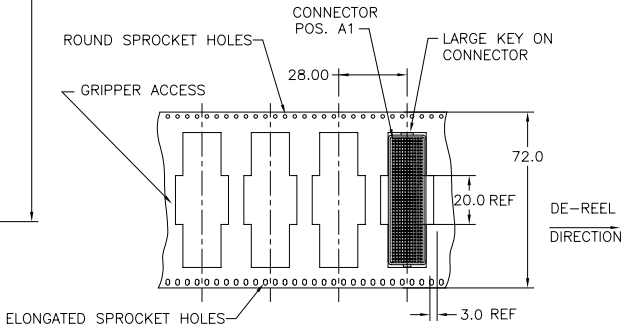
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DIM. A	PLUG ASSY P/N	RECPT. ASSY P/N
6.0	84740	74388
12.0	84520	74388

MATED HEIGHT AFTER REFLOW IS BASED ON ϕ .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE



TAPE & REEL PACKAGING SCALE NONE PER EIA 481-3

mat'l code	SEE NOTE 1	surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family	MEG-ARRAY
ltr	ec'n no	dr	date	tolerances unless otherwise specified		MM	title	6mm RECPT. ASSY. 10x40= 400 POS.
K				angles	Xx3	scale	2:1	dwg no
				or ±2°	XXX-B			74388
				dr	D WAUGHEN	1.5.98		sheet 2 of 3
				enqr	T LEMKE	1.5.98		size
				chr	T LEMKE	1.5.98		A4
				appd	T LEMKE	1.5.98		type
								CUSTOMER Drawing
sheet index	revision sheet							

NOTES:

① **MAT'L:**

HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING

CONTACT: (SEE TABLE ON SHEET1)
 SOLDER BALL: (SEE TABLE ON SHEET1)
 EUTECTIC SnPb OR LEAD FREE
 95.5Sn/4Ag/0.5Cu

- ② SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- ③ MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- ④ PLATING FOR -2XX SERIES DASH NOS: Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- ⑤ FOR PROPER APPLICATION FOLLOW FCJ APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCJ APPLICATION SPECIFICATION
- ⑥ THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

mat'l code		SEE NOTE 1		surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family	MEG-ARRAY		
ltr	ecrn no	dir	date	tolerances unless otherwise specified				MM	title	6mm RECP. ASSY. 10x40= 400 POS.		
K				angles	30		X*3 XXX*B XXX*051	scale	2:1	dwg no	sheet 3 of 3	size
				or ±2"						74388		A4
				dr	D WAUGHEN	1.5.98						
				engr	T LEMKE	1.5.98						
				chr	T LEMKE	1.5.98						
				appd	T LEMKE	1.5.98						
sheet index	revision sheet											